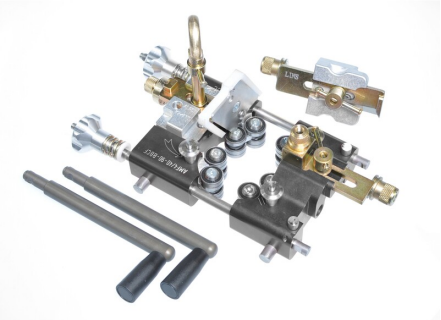
/ CAMF4/40-90-BBCF

Multifunction tool for bonded semiconductor and insulation

See online technical sheet



/ Use

CAMF SERIE tools enable the user to :
- remove the bonded semiconductor
- remove the insulation

Bonded semiconductor removal : very steady (16 ball bearings around the cable), shaping the cable round over the insulation, constant diameter over the insulation, prevent the blade from diging into the insulation

Insulation removal : back-iron that enables the user to tune the pitch od the tool thus making the rotation of the tool easy when removing the insulaton

/ Advantages

- No silicon needed
- Smooth finish
- Robust design
- Counter-iron to regulate tool feed and facilitate rotation
- Motorised option
- Cable rounding
- Adjustment of the tool feed (chip thickness)
- Reduces sanding time - AC Insulator
- Minimum roughness on the insulator (DC)
- All-in-one capability - K7 (K7/GNS, K7/PNS, K7/CH)

/ Areas of activity

- Cable & Connections
- Industry
- Production

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/ Technical specifications

- **Cable tools :** Cable tools
- **For network cables :** HTB
- **Max diameter (mm) :** 90
- **Mini diameter (mm) :** 40
- **Cut deepness (mm) :** 35
- **Remining length of semi conductor (MIN) (mm) :** 55
- **Scoring depth MAX (mm) :** 2,5
- **Lenght (mm) :** 460
- **Width (mm) :** 155
- **Height (mm) :** 150
- **Weight (kg) :** 3,9
- **Packaging :** Case

/ Accessories

	Reference	Designation
	**ET-AMF4**	Motorization for AMF4

/ Spare parts

	Reference	Designation
	**LFNS**	LFNS
	**LINS**	LINS

/ Associated products

	Reference	Designation
	GRI	Scraper for semiconductor residues
	**CHN2/25-60-NS**	Alrocone tool to taper shape on insulation without silicone
	**DMSR/40-90**	Stripping tool for HV and EHV cable's outer sheath and shield

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